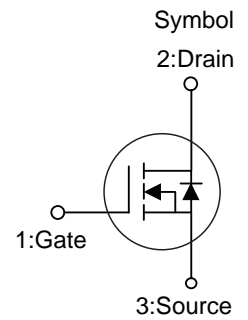


■ PRODUCT CHARACTERISTICS

V_{DSS}	100V
$R_{DS(ON) Typ} (@V_{GS}=10V)$	75m Ω
$R_{DS(ON) Typ} (@V_{GS}=4.5V)$	81m Ω
I_D	15A



■ APPLICATIONS

- * Electronic lamp ballasts based on half bridge
- * Load Switching, Quick/Wireless Charge.
- * Motor Driving

■ FEATURE

- * Low Gate Charge
- * Pb-Free Lead Plating



TO-251

■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT15N10C	TO-251	70 pieces/Tube

■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current Continuous ($@V_{GS}=10V, T_A=25^{\circ}C$)	I_D	15	A
Drain Current Continuous ($@V_{GS}=10V, T_A=100^{\circ}C$)	I_D	10.6	A
Drain Current Pulsed	I_{DM}	60	A
Avalanche Energy *	E_{AS}	50	mJ
Power Dissipation	P_D	50	W
Junction Temperature	T_J	+150	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}C$

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R_{thJC}	2.5	$^{\circ}C/W$

Note: * EAS condition: $T_J=25^{\circ}C, V_{DD}=40V, V_G=10V, L=1mH, R_g=25\Omega$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Drain to Source Leakage Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$	-	-	1	μA
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+20V, V_{DS}=0V$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-20V, V_{DS}=0V$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=8A$	-	75	95	$m\Omega$
		$V_{GS}=4.5V, I_D=8A$	-	81	100	$m\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.5	V
Dynamic characteristics						
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, f=1.0MHz$	-	1.5	-	Ω
Forward Transconductance	g_{fs}	$V_{DS}=5V, I_D=5A$	10	-	-	S
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V$ $f=1.0MHz$	-	980	-	pF
Output Capacitance	C_{oss}		-	30	-	pF
Reverse Transfer Capacitance	C_{rss}		-	25	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=10V, V_{DS}=50V,$ $I_D=8A, R_G=3\Omega$	-	15	-	ns
Rise Time	t_r		-	5	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	25	-	ns
Fall Time	t_f		-	7	-	ns
Total Gate Charge	Q_g	$I_D=8A, V_{DS}=50V$ $V_{GS}=10V$	-	22.3	-	nC
Gate to Source Charge	Q_{gs}		-	2.87	-	nC
Gate to Drain("Miller") Charge	Q_{gd}		-	6.14	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I_S		-	-	15	A
Maximum Pulsed Current(Body Diode)	I_{SM}		-	-	60	A
Diode Forward Voltage	V_{SD}	$I_{SD}=1A, V_{GS}=0V$	-	0.72	1.2	V
Reverse Recovery Time	t_{rr}	$I_{SD}=8A, T_J=25^{\circ}\text{C}$ $di/dt=100A/\mu s$	-	38	-	ns
Reverse Recovery Charge	Q_{rr}		-	27	-	nC

■ TYPICAL CHARACTERISTICS

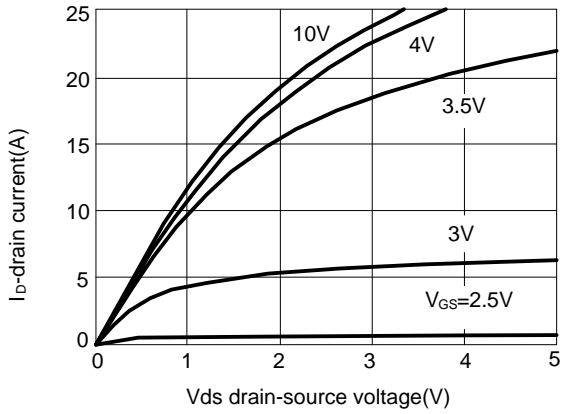


Figure 1 :Output characteristics

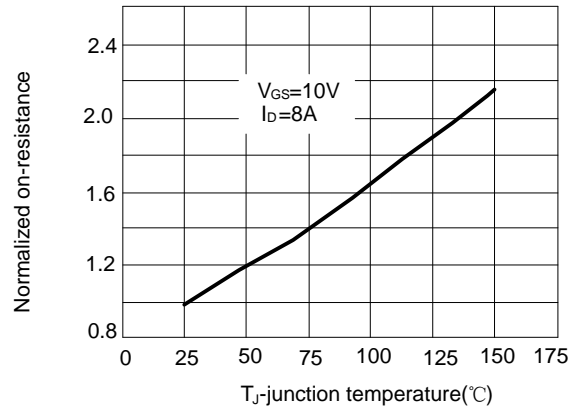


Figure 2 :Rds(on)-junction temperature

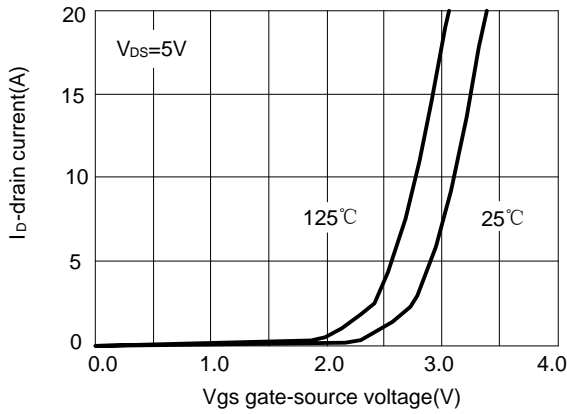


Figure 3 :Transfer characteristics

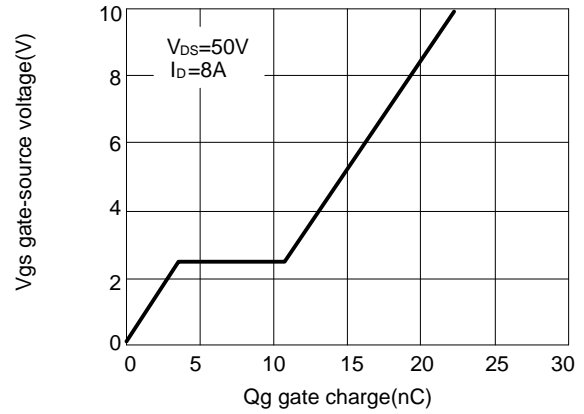


Figure 4 :Gate charge

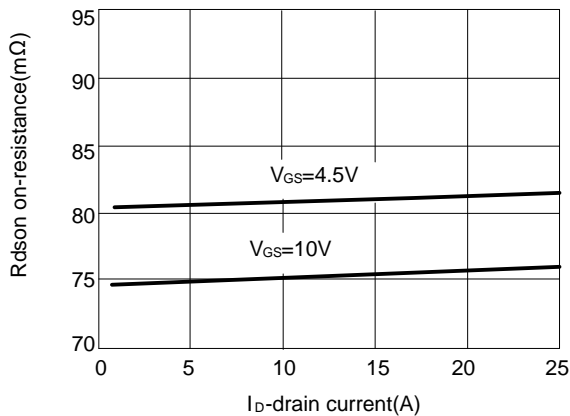


Figure 5 :Rds(on)-drain current

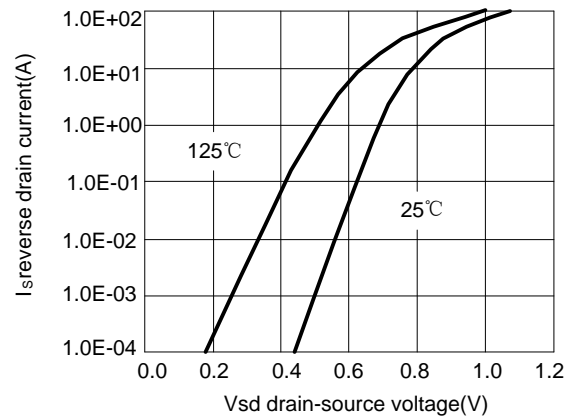


Figure 6 :Source-drain diode forward

■ TYPICAL CHARACTERISTICS(Cont.)

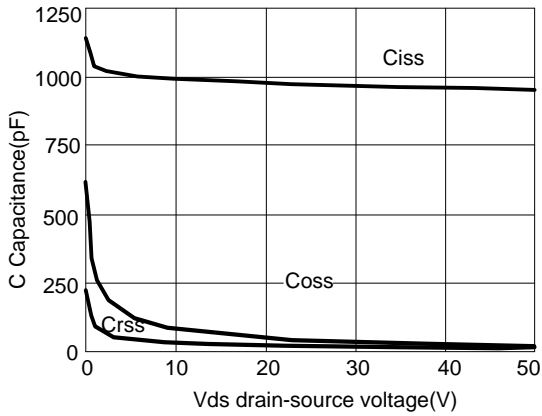


Figure 7 :Capacitance vs. vds

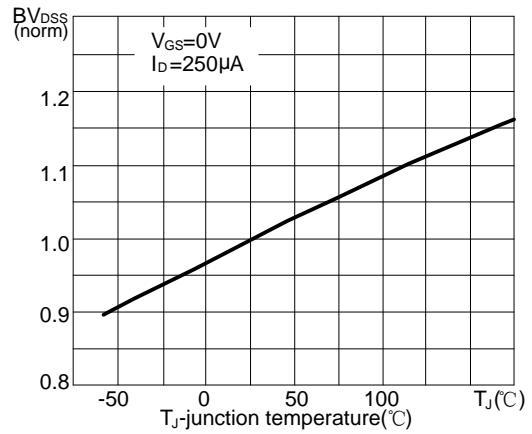


Figure 8 BVdss vs.junction temperature

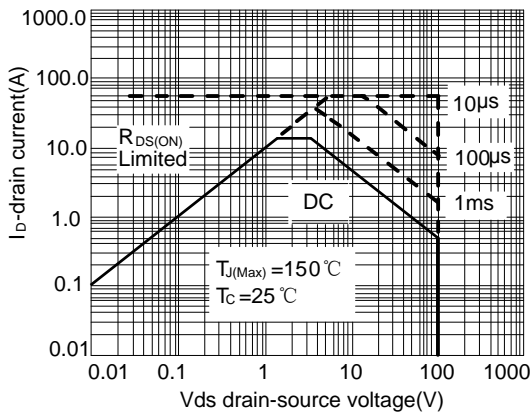


Figure 9 :Safe operation area

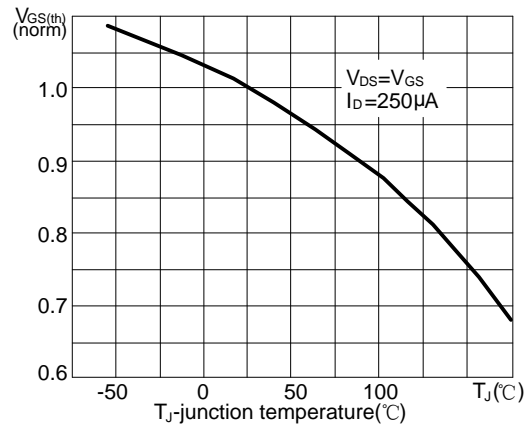


Figure 10 Vgs(th) vs.junction temperature

■ TO-251 PACKAGE OUTLINE DIMENSIONS

